

**ADVANCE DATA SHEET**

# SKY77436 Front-End Module for WCDMA / HSDPA / HSUPA Band V (Tx 824-849 MHz), (Rx 869-894 MHz)

**Applications**

- Digital cellular (WCDMA) handsets

**Features**

- High Speed Downlink Packet Access (HSDPA)
- High Speed Uplink Packet Access (HSUPA)
- Low quiescent current - 16 mA
- Low current consumption - 450 mA
- Integrated Power Detector
- 16-pad package
- Small package - 7 mm x 4 mm
- Low profile - 1.15 mm, Max.
- Low voltage - 3.1 V to 4.45 V
- Digital enable pad
- Highly integrated, user friendly solution
- InGaP HBT
- Integrated interstage filter and duplexer
- Requires few external components

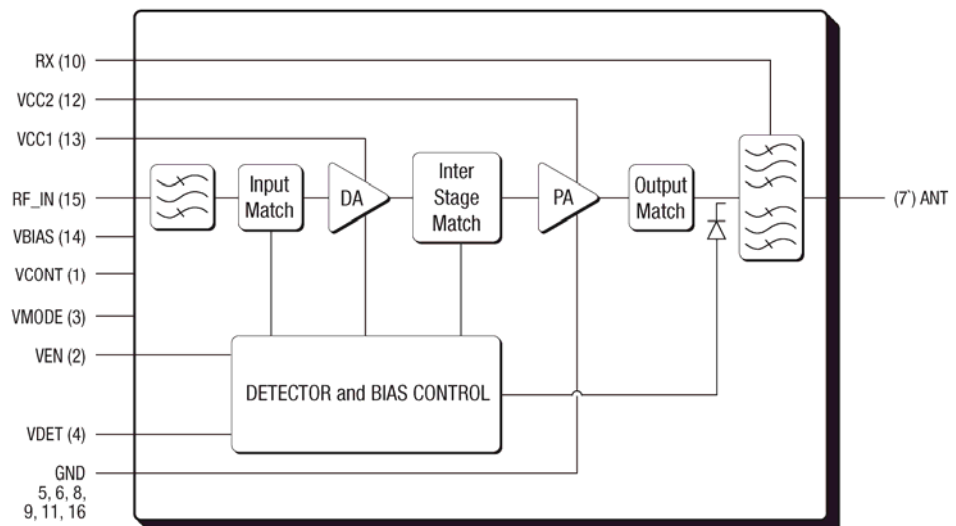
**Description**

The SKY77436 Front-End Module (FEM) is a fully matched, 16-pad surface mount module developed for WCDMA applications. Small and efficient, this WCDMA FEM integrates the interstage filter, the input matching, the power amplifier, the output matching, the power detection, and the duplexer into a single 7 mm x 4 mm x 1.15 mm package.

The SKY77436 meets the stringent spectral requirements of WCDMA standards up to 25.0 dBm output power. The FEM incorporates an InGaP HBT PA and contains circuitry to optimize power detector performance. Different control pads are available to enhance the performance of the FEM at different power levels.

Integration of the RF front-end greatly simplifies the design of the handset radio as all critical matching between the interstage filter, PA, power detection, and duplexer is optimized within the module. By optimizing the efficiency of the InGaP HBT PA MMIC and reducing the RF loss between the integrated components, this FEM achieves current as low as 410 mA at maximum output power (25.0 dBm) that significantly improves the talk time of the WCDMA handset. This small package uses Skyworks' low cost, multi-laminate substrate technology and is approximately half the size of individually-packaged component solutions. The SKY77436 front-end module can save handset designers significant board space and design-cycle time.

**NEW** Skyworks Green™ products are lead (Pb)-free, RoHS (Restriction of Hazardous Substances)-compliant, conform to the EIA/EICTA/JEITA Joint Industry Guide (JIG) Level A guidelines, and are free from antimony trioxide and brominated flame retardants.

**Figure 1. Functional Block Diagram**

**Electrical Specifications**

The following tables list the electrical characteristics of the SKY77436 Front-End Module for WCDMA. Table 1 lists the absolute maximum ratings and Table 2 specifies the recommended operating conditions necessary to achieve the electrical performance listed in Table 3. Table 4 through Table 7 defines the standard test configurations for WCDMA, HSDPA, and

HSUPA modes. Table 8 lists the parameters specific to power detection performance over the recommended operating conditions, including mismatch at the module antenna port up to a VSWR of 2.5:1 for all phase angles. Table 9 presents nominal duplexer performance data.

**Table 1. Absolute Maximum Ratings<sup>1</sup>**

Parameter	Symbol	Minimum	Nominal	Maximum	Unit	
RF Input Power	P <sub>IN</sub>	—	—	10.0	dBm	
Supply Voltages	No RF	V <sub>CC1</sub> , V <sub>CC2</sub> , V <sub>BIAS</sub>	—	3.4	6.0	Volt
	With RF		—	3.4	4.7	Volt
Bias Control Voltage	V <sub>CONT</sub>	—	—	2.7	Volt	
Mode Control Voltage	V <sub>MODE</sub>	—	—	3.0	Volts	
Enable Control Voltage	V <sub>EN</sub>	—	—	3.0	Volt	
Temperatures	Operating	T <sub>CASE</sub>	-20	+25	+110	°C
	Storage	T <sub>STG</sub>	-55	—	+125	

<sup>1</sup> No damage assuming only one parameter at a time is set to limit with all other parameters set at nominal values.

**Table 2. Recommended Operating Conditions**

Parameter	Symbol	Minimum	Nominal	Maximum	Unit	
Tx Channel Center Frequency	F <sub>TX</sub>	826.4	836.5	846.6	MHz	
Rx Channel Center Frequency	F <sub>RX</sub> = F <sub>TRX</sub> + 45 MHz	871.4	881.5	891.6	MHz	
Supply Voltages	V <sub>CC1</sub> , V <sub>CC2</sub>	3.1 <sup>1</sup>	3.4	4.45	Volt	
	V <sub>BIAS</sub>	3.1	3.4	4.45		
Bias Control Voltage	V <sub>CONT</sub>	0.5	—	1.9	Volt	
Mode Control	Low Power Mode (LPM)	V <sub>MODE_L</sub>	1.5	1.8	2.86	Volt
	High Power Mode (HPM)	V <sub>MODE_H</sub>	0.0	0.0	0.56	
Enable Control Setting	Disabled	V <sub>EN_L</sub>	0.0	0.0	0.56	Volt
	Enabled	V <sub>EN_H</sub>	1.5	1.8	2.86	
Operating Temperature	T <sub>CASE</sub>	-20	+25	+85	°C	

<sup>1</sup> For V<sub>CC</sub> < 3.4 V, maximum output power = P<sub>MAX2</sub>

**Table 3. Electrical Specifications for Nominal Operating Conditions <sup>1</sup>**

WCDMA (Wide Band Code Division Multiple Access)							
Characteristic		Symbol	Conditions	Minimum	Typical	Maximum	Unit
Linear Output Power		P <sub>MID</sub>	V <sub>CC</sub> ≥ 3.1 V HPM, LPM	10.0	—	—	dBm
		P <sub>MAX2</sub> <sup>2</sup>	V <sub>CC</sub> ≥ 3.1 V HPM	24.2	—	—	
		P <sub>MAX1</sub> <sup>2</sup>	HPM	25.0	—	—	
Gain	Mid Power	G <sub>MID</sub>	LPM P <sub>MID</sub>	13.0	—	23.0	dB
	High Power	G <sub>HIGH</sub>	P <sub>MAX1</sub>	21.5	—	30.0	
Gain Flatness Over Frequency		ΔG <sub>PWR</sub>	Each Tx Frequency	-2.5	—	2.5	dB
Current Consumption	Mid Power	I <sub>CC</sub>	LPM P <sub>MID</sub>	—	—	50	mA
	High Power		P <sub>MAX1</sub>	—	—	450	
Power Added Efficiency	Mid Power	PAE <sub>MID</sub>	LPM P <sub>MID</sub>	5.5	—	—	%
	High Power	PAE <sub>HIGH</sub>	P <sub>MAX1</sub>	22.5	—	—	
Error Vector Magnitude		EVM	—			5	%
Adjacent Channel Leakage Ratio <sup>3</sup>	5 MHz	ACL1	—	—	-40	—	dBc
	10 MHz	ACL2		—	-54	—	
Harmonic Suppression	Second	f <sub>H2</sub>	P <sub>MAX1</sub>	—	—	-33	dBm
	Third	f <sub>H3</sub>		—	—	-33	
Tx Noise Power in Rx Band		NR <sub>X</sub>	RBW = 3.84 MHz	—	—	-114	dBm
Input Voltage Standing Wave Ratio		V <sub>SWR</sub>	—	—	—	2.5:1	
Quiescent Current		I <sub>CO</sub>	—	—	—	16	mA
Control Current		I <sub>CONT</sub>	—	—	—	1	mA
Enable Current		I <sub>EN</sub>	—	—	—	1	mA
Leakage Current		I <sub>LEAK</sub>	V <sub>CC1</sub> , V <sub>CC2</sub> , V <sub>BIAS</sub> = 4.45 V V <sub>CONT</sub> = 0 V V <sub>EN</sub> = 0 V V <sub>MODE</sub> = 0 V	—	—	20	μA
Stability (spurious output)		S	8:1 VSWR, all phases	—	—	-65	dBc
Ruggedness <sup>4</sup>		R <sub>u</sub>	—	10:1	—	—	—

<sup>1</sup> Unless otherwise specified: V<sub>CC</sub> = 3.4 V, Temp. = 25 °C.

<sup>2</sup> For STC1 WCDMA, STC2 HSDPA, and STC3 HSUPA modes test conditions. For STC4 HSUPA, power backoff = 2.6 dB.

<sup>3</sup> ACLR is specified per 3GPP as the ratio of in-band power to adjacent power, both measured in 3.84 MHz bandwidth at specified offsets.

<sup>4</sup> All phases, time = 10 seconds, continuous WCDMA / HSDPA modulated signal.

**Table 4. Standard Test Configuration – STC1 WCDMA Mode**

Parameter	Level	Spread Code	Spread Factor	I/Q	$\beta_c$	$\beta_d$	$\beta_{hs}$	$\beta_{ec}$	$\beta_{ed}$	Relative Power (dB)
DPCCH	15 kbps	0	256	Q	8/15	—	—	—	—	-6.547
DPDCH	60 kbps	16	64	I	—	15/15	—	—	—	-1.087

**Table 5. Standard Test Configuration – STC2 HSDPA Mode**

Parameter	Level	Spread Code	Spread Factor	I/Q	$\beta_c$	$\beta_d$	$\beta_{hs}$	$\beta_{ec}$	$\beta_{ed}$	Relative Power (dB)
DPCCH	15 kbps	0	256	Q	12/15	—	—	—	—	-7.095
DPDCH	60 kbps	16	64	I	—	15/15	—	—	—	-5.157
HS-DPCCH	15 kbps	64	256	Q	—	—	24/15	—	—	-3.012

**Table 6. Standard Test Configuration – STC3 HSUPA Mode**

Parameter	Level	Spread Code	Spread Factor	I/Q	$\beta_c$	$\beta_d$	$\beta_{hs}$	$\beta_{ec}$	$\beta_{ed}$	Relative Power (dB)
DPCCH	15 kbps	0	256	Q	8/15	—	—	—	—	-19.391
DPDCH	960 kbps	1	4	I	—	15/15	—	—	—	-13.931
HS- DPCCH	15 kbps	64	256	Q	—	—	8/15	—	—	-19.391
E-DPCCH	15 kbps	1	256	I	—	—	—	10/15	—	-17.338
E-DPDCH	960 kbps	2	4	I	—	—	—	—	71.5/15	-0.371

**Table 7. Standard Test Configuration – STC4 HSUPA Mode**

Parameter	Level	Spread Code	Spread Factor	I/Q	$\beta_c$	$\beta_d$	$\beta_{hs}$	$\beta_{ec}$	$\beta_{ed}$	Relative Power (dB)
DPCCH	15 kbps	0	256	Q	6/15	—	—	—	—	-12.499
DPDCH	960 kbps	1	4	I	—	15/15	—	—	—	-4.540
HS- DPCCH	15 kbps	64	256	Q	—	—	2/15	—	—	-22.041
E-DPCCH	15 kbps	1	256	I	—	—	—	12/15	—	-6.478
E-DPDCH	960 kbps	2	4	I	—	—	—	—	15/15	-4.425

**Table 8. Electrical Specifications for Power Detector**

Tx Power Detection						
Characteristic	Symbol	Conditions	Minimum	Typical	Maximum	Unit
Power Detect Range	P <sub>DET</sub>		0.0	—	26.0	dBm
Detector Output Range	V <sub>DET</sub>	3 dBm ≤ P <sub>0</sub> ≤ 26 dBm	400 (rms)	—	1800 (peak)	mV

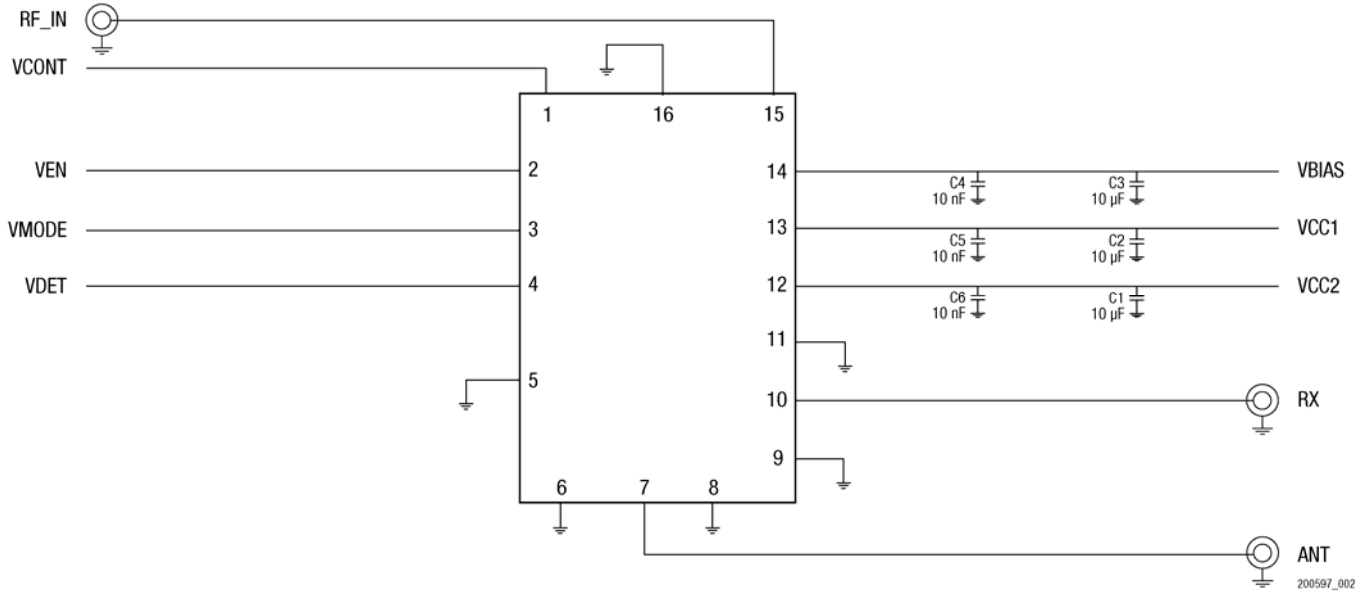
**Table 9. Nominal Duplexer Performance**

Antenna to Rx Parameter						
Characteristic	Symbol	Conditions	Minimum	Typical	Maximum	Unit
Insertion Loss	IL <sub>Rx</sub>	869 MHz to 894 MHz	—	—	3.5	dB
Ripple		Each Rx Frequency	-0.5	—	0.5	dB
Attenuation		DC to 12750 MHz	20	—	—	dB
		A <sub>Rx1</sub>	35 MHz to 55 MHz	40	—	
		A <sub>Rx2</sub>	289 MHz to 298 MHz	25	—	
		A <sub>Rx3</sub>	434 MHz to 447 MHz	45	—	
		A <sub>Rx4</sub>	779 MHz to 804 MHz	30	—	
	Tx Band	A <sub>Rx5</sub>	824 MHz to 849 MHz	50	—	
		A <sub>Rx6</sub>	849 MHz to 869 MHz	2	—	
		A <sub>Rx7</sub>	914 MHz to 1693 MHz	15	—	
		A <sub>Rx8</sub>	1693 MHz to 1743 MHz	35	—	
	A <sub>Rx9</sub>	2517 MHz to 2592 MHz	35	—		
VSWR		—	—	—	2.0:1	—
Input		—	—	—	15	dBm
Tx Power @ Rx Port		826.4 MHz to 846.6 MHz P <sub>MAX1</sub>	—	—	-25	dBm

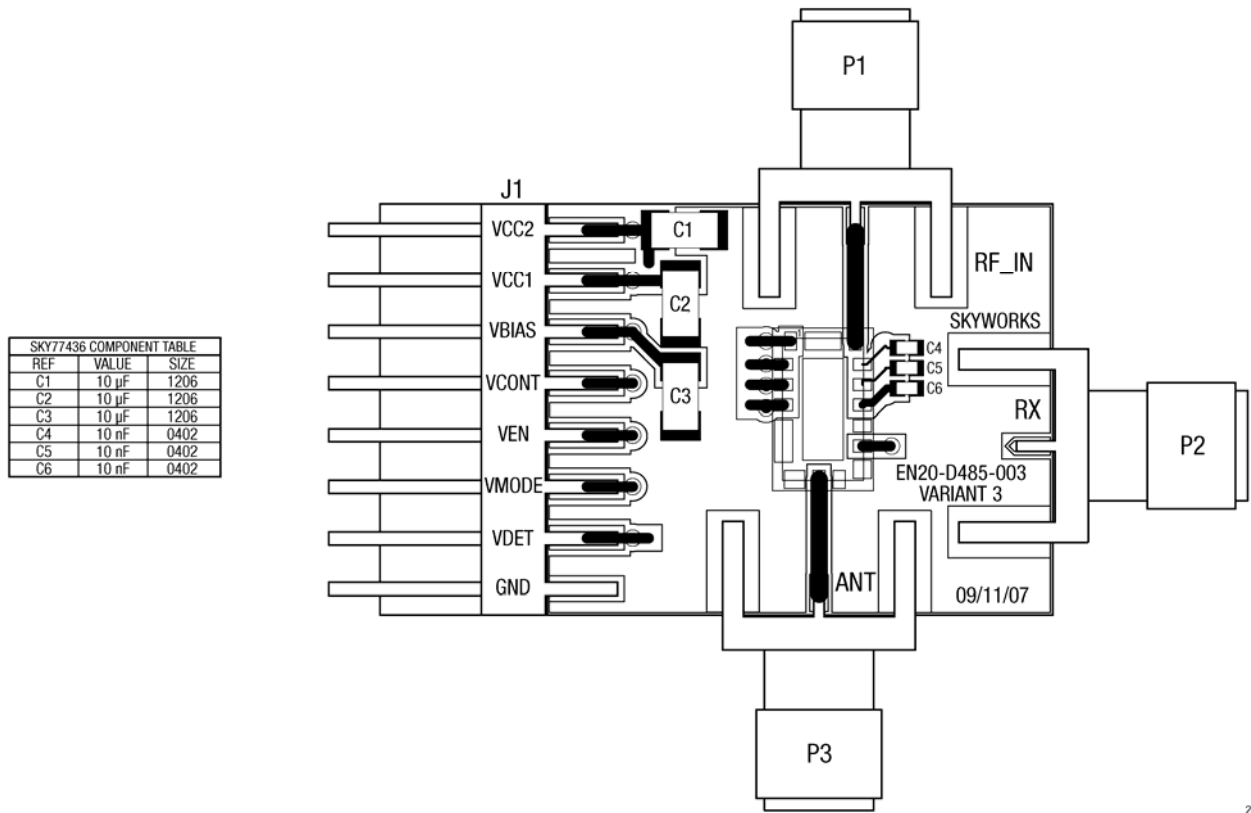
**Evaluation Board Description**

The evaluation board is a platform for testing and interfacing design circuitry. To accommodate the interface testing of the SKY77436, the evaluation board schematic and assembly

diagrams are included for preliminary analysis and design. The basic schematic is shown in Figure 2 for the board assembly in Figure 3.



**Figure 2. Evaluation Board Schematic Diagram**

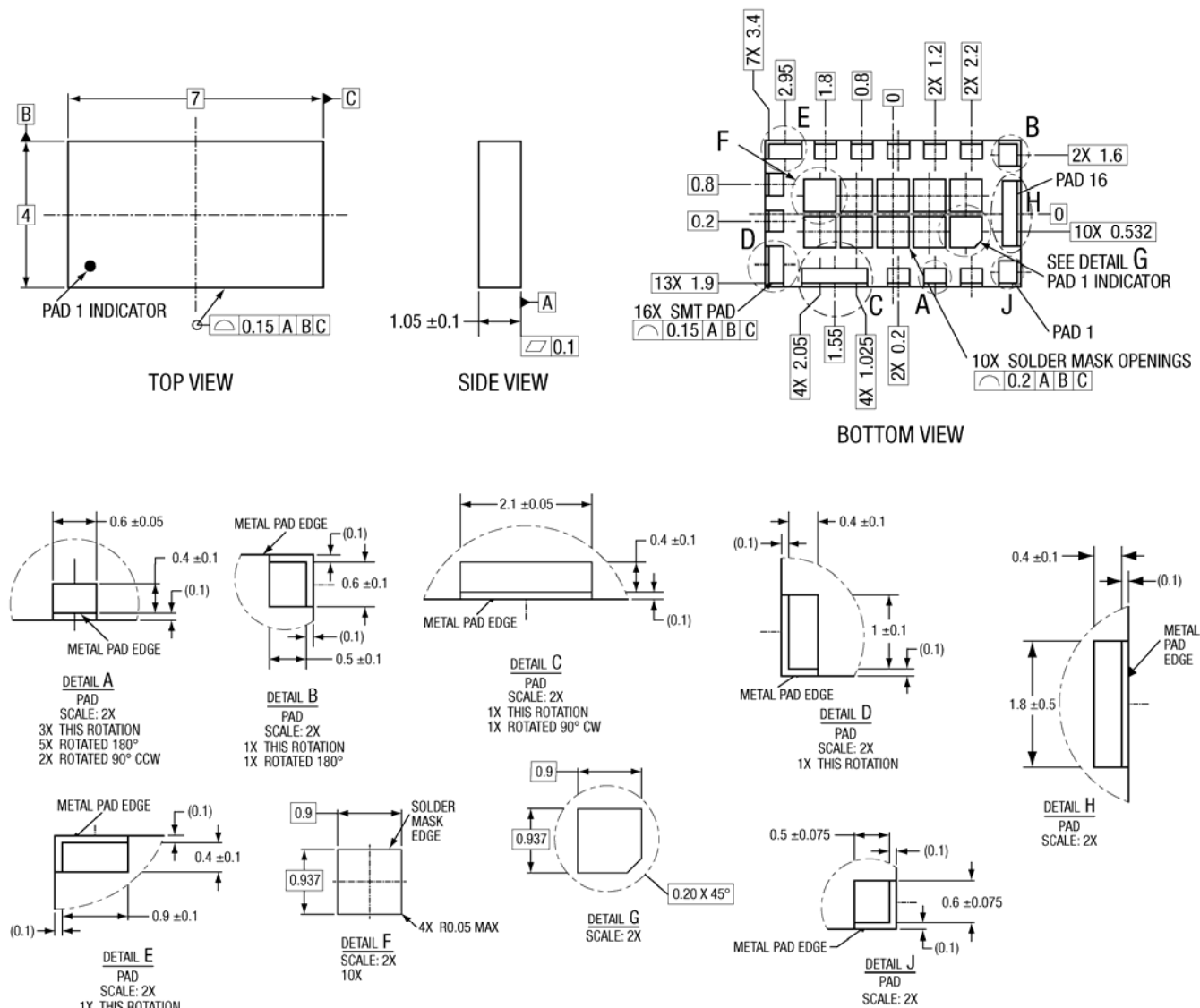


**Figure 3. Evaluation Board Assembly Diagram**

### Package Dimensions

The SKY77436 is a multi-layer laminate base, overmold encapsulated modular package designed for surface-mounted solder attachment to a printed circuit board. Figure 4 is a mechanical drawing of the pad layout for this package. Figure 5

provides a recommended phone board layout footprint for the FEM to help the designer attain optimum thermal conductivity, good grounding, and minimum RF discontinuity for the 50-ohm terminals.

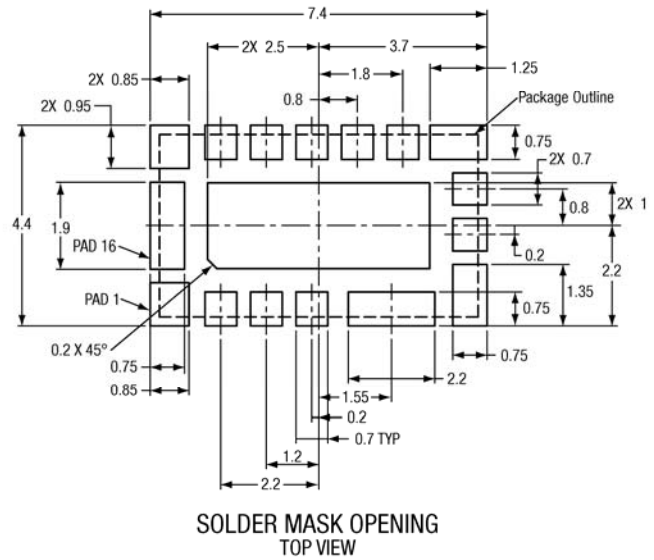
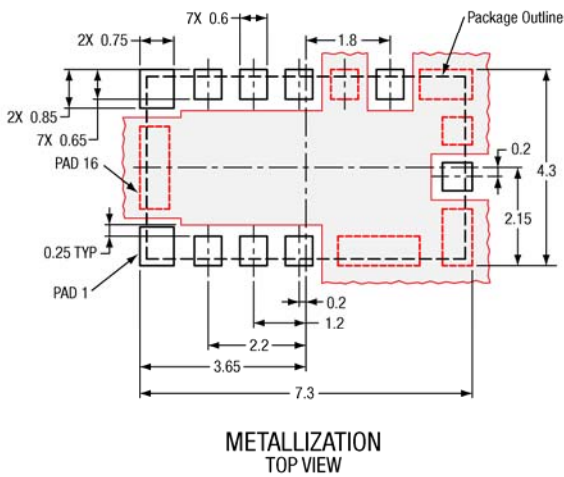
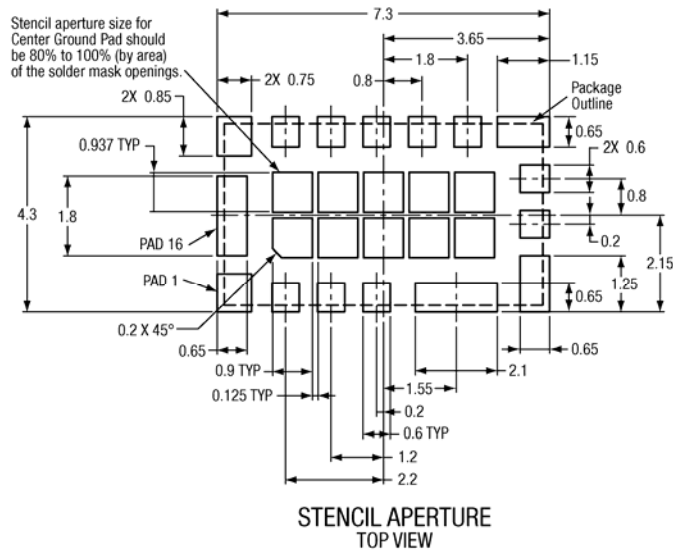


NOTES: UNLESS OTHERWISE SPECIFIED.

1. DIMENSIONING AND TOLERANCING IN ACCORDANCE WITH ASME Y14.5M-1994.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. PADS ARE SOLDER MASK DEFINED ON 3 EDGES & METAL DEFINED ON 1 EDGE.

DS00089-2 REV. 1  
200597\_004

Figure 4. Dimensional Diagram for 7 x 4 x 1.05 mm, 16-Pad Package (All Views) – SKY77436



- NOTES: UNLESS OTHERWISE SPECIFIED.
1. DIMENSIONING AND TOLERANCING IN ACCORDANCE WITH ASME Y14.5M-1994.
  2. ALL DIMENSIONS ARE IN MILLIMETERS.

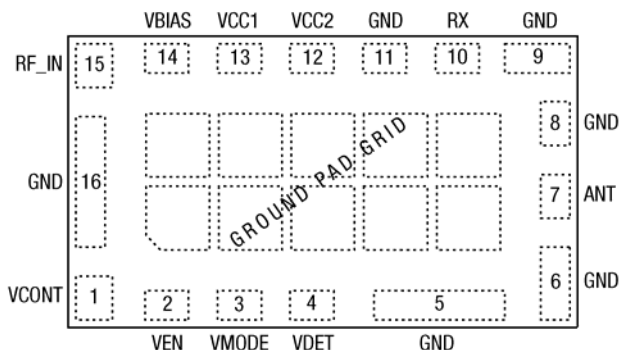
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Figure 5. Phone PCB Layout Footprint for 7 x 4 mm, 16-pad Package – SKY77436



## Package Description

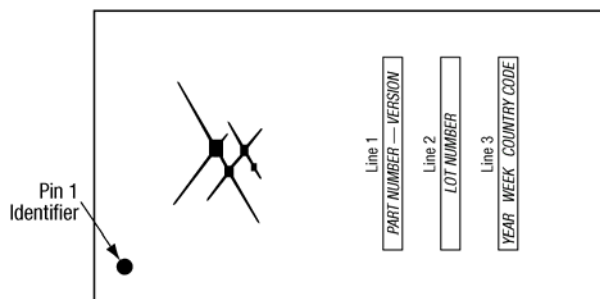
Figure 6 shows each pad name and the pad numbering convention, which starts with pad 1 in the lower left, as indicated, and increments counter-clockwise around the package. Figure 7 illustrates typical case markings.



Pad layout as seen from Top View looking through package.

200597\_006

Figure 6. SKY77436 16-pad Configuration – (Top View)



NOTE: SKY77436  
Lines 1, 2, 3 have a maximum of 11 characters  
YEAR = Year of Manufacture  
WEEK = Week Package Was Sealed  
Country Code = Country of Manufacture (MX)

200597\_006

Figure 7. Typical Case Markings (Top View)

## Package Handling Information

Because of its sensitivity to moisture absorption, this device package is baked and vacuum-packed prior to shipment. Instructions on the shipping container label must be followed regarding exposure to moisture after the container seal is broken, otherwise, problems related to moisture absorption may occur when the part is subjected to high temperature during solder assembly.

The SKY77436 is currently qualified for MSL3/260 °C. Care must be taken when attaching this product, whether it is done manually or in a production solder reflow environment. If the part is attached in a reflow oven, the temperature ramp rate should not exceed 3 °C per second; maximum temperature should not exceed 260 °C. If the part is manually attached, precaution should be taken to insure that the part is not subjected to temperatures exceeding 260 °C for more than 10 seconds. For details on attachment techniques, precautions, and handling procedures recommended by Skyworks, please refer to Skyworks Application Note: *PCB Design and SMT Assembly/Rework*, Document Number 101752. Additional information on standard SMT reflow profiles can also be found in the *JEDEC Standard J-STD-020*.

Production quantities of this product are shipped in the standard tape-and-reel format. For packaging details, refer to Skyworks Application Note: *Tape and Reel – RF Modules*, Document Number 101568.

## Electrostatic Discharge (ESD) Sensitivity

To avoid ESD damage, both latent and visible, it is very important that the product assembly and test areas follow the Class 1 ESD handling precautions listed below.

- Personnel Grounding
  - Wrist Straps
  - Conductive Smocks, Gloves and Finger Cots
  - Antistatic ID Badges
- Protective Workstation
  - Dissipative Table Top
  - Protective Test Equipment (Properly Grounded)
  - Grounded Tip Soldering Irons
  - Solder Conductive Suckers
  - Static Sensors
- Facility
  - Relative Humidity Control and Air Ionizers
  - Dissipative Floors (less than 10<sup>9</sup> Ω to GND)
- Protective Packaging and Transportation
  - Bags and Pouches (Faraday Shield)
  - Protective Tote Boxes (Conductive Static Shielding)
  - Protective Trays
  - Grounded Carts
  - Protective Work Order Holders

## Ordering Information

Model Number	Manufacturing Part Number	Product Revision	Package	Operating Temperature
SKY77436	SKY77436		MCM 4 x 7 x 1.05 mm	-20 °C to +85 °C

## Revision History

Revision	Date	Description
A	October 15, 2008	Initial Release – Advance Information
B	November 18, 2008	Revise: Figure 3
C	December 8, 2008	Revise: Table 8

## References

Application Note: Tape and Reel – RF Modules, Document Number 101568

Application Note: PCB Design and SMT Assembly/Rework, Document Number 101752

JEDEC Standard JESD22-A114 Human Body Model (HBM)

JEDEC Standard JESD22-A115 Machine Model (MM)

JEDEC Standard JESD22-C101 Charged Device Model (CDM)

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